



(19)

Generated Document

(11) Publication number: **06073598 A****PATENT ABSTRACTS OF JAPAN**(21) Application number: **03133502**(51) Int'l. Cl.: **C25D 17/00 C25D 5/08 H01L 21/288**(22) Application date: **08.05.91**

(30) Priority:

(43) Date of application publication: **15.03.94**

(84) Designated contracting states:

(71) Applicant: **SUGANUMA KEIICHIRO**(72) Inventor: **SUGANUMA KEIICHIRO**

(74) Representative:

**(54) METHOD FOR
PRODUCING
SEMICONDUCTOR AND
DEVICE THEREFOR**

(57) Abstract:

PURPOSE: To subject a semiconductor wafer to plating in a uniform thickness and to carry out chemical treatment or other treatment.

CONSTITUTION: A semiconductor wafer W is held over a treating vessel I with the top open so that the surface of the wafer W to be treated is positioned downward, a treating soln. is fed from plural parts in the treating vessel I and electric current is supplied between a lower electrode 2 and an upper electrode 3 disposed in the vessel I while allowing the treating soln. to overflow the vessel I to subject the semiconductor wafer W to plating, chemical treatment or other treatment.

COPYRIGHT: (C)1994,JPO&Japio

BEST AVAILABLE COPY

600/3598 A

Page 2 of 2

